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PTO/SB/08a/b (08-03)  
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<b>Substitute for form 1449A/B/PTO</b>  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (Use as many sheets as necessary)				<b>Complete if Known</b>	
				Application Number	10/723,363
				Filing Date	November 26, 2003
				First Named Inventor	Mark E. Tuttle
				Art Unit	2621 2624
				Examiner Name	Not Yet Assigned Amara Abdi
Sheet	1	of	1	Attorney Docket Number	108298746US

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code <sup>2</sup> (if known)			
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NON PATENT LITERATURE DOCUMENTS			
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Examiner Signature	/Amara Abdi/	Date Considered	01/31/2008
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<b>Substitute for form 1449A/B/PTO</b>  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (Use as many sheets as necessary)				<b>Complete If Known</b>	
				Application Number	10/723,363-Conf. #9952
				Filing Date	November 26, 2003
				First Named Inventor	Mark E. Tuttle
				Art Unit	26212624
				Examiner Name	Not Yet Assigned Amara Abdi
Sheet	6	of	6	Attorney Docket Number	108298746US

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